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4 – 6 June 2018**



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Optical Interconnects Conference 2018

4-6 June 2018
Hilton Santa Fe Historic Plaza
Santa Fe, New Mexico USA

MA - Opening Remarks and Next Generation Optical Interconnects I - 8:30 am–10:00 am - Mesa Ballroom

MA.1: The ARPA-E ENLITENED Program: Will Co-Packaged Integrated Photonic Interconnects Transform Future Data-Centers? (Page N/A)

Michael Haney (*ARPA*)

MA.2: High Speed, Low Energy, Low Latency, and Low Cost Optical Interconnect for Servers and Data Centers (Page N/A)

Daniel Kuchta (*IBM T. J. Watson Research Center*)

MB - Advance Silicon Photonics Devices I - 10:15 am–11:45 am - Mesa Ballroom

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Meisam Bahadori (*Columbia University*)
Sebastien Rumley (*Columbia University*)
Qixiang Cheng (*Columbia University*)
Keren Bergman (*Columbia University*)

MB.2: Improving Microresonators Reliability in Silicon Photonic Integrated Circuits (Page 3)

Mahdi Nikdast (*Colorado State University*)
Gabriela Nicolescu (*Polytechnique Montréal*)
Odile Liboiron-Ladouceur (*McGill University*)

MB.3: A Stable Ultrahigh Extinction Silicon Photonic Amplitude Modulator (Page 5)

Hong Cai (*Sandia National Laboratories*)
Sheng Liu (*Sandia National Laboratories*)
Andrew Pomerene (*Sandia National Laboratories*)
Douglas C. Trotter (*Sandia National Laboratories*)
Andrew L. Starbuck (*Sandia National Laboratories*)
Christina Dallo (*Sandia National Laboratories*)
Dana Hood (*Sandia National Laboratories*)
Christopher T. DeRose (*Sandia National Laboratories*)
Anthony L. Lentine (*Sandia National Laboratories*)

MB.4: Thermal Effect on Semi-Conductor and Metal Heaters in FP-Based Modulator Using Thermal Simulation (Page 7)

M. Atif (*Technische Universität Berlin, Sicoya GmbH, and GC University*)
S. Mahdi (*Technische Universität Berlin*)
S. Kupijai (*Sicoya GmbH*)
C. Theiss (*Sicoya GmbH*)
H. Rhee (*Sicoya GmbH*)
A. Al-Saadi (*Sicoya GmbH*)
M. Henniges (*Technische Universität Berlin and Sicoya GmbH*)
D. Selicke (*Technische Universität Berlin and Sicoya GmbH*)
M. Vitali (*Sicoya GmbH*)
L. Yan (*Sicoya GmbH*)
D. Bronzi (*Sicoya GmbH*)
U. Woggon (*Technische Universität Berlin*)
S. Meister (*Sicoya GmbH*)

MB.5: Energy-Efficient Microsecond Silicon Photonic Switches (Page N/A)

Ming Wu (*University of California, Berkeley*)

MC - Advance Optical Co-Packaging - 1:30 pm–3:15 pm - Mesa Ballroom

MC.1: The PhotonicPlug - Scaling Up Silicon Photonics Packaging (Page 9)

Hesham Taha (*Teramont Ltd.*)

MC.2: Glass Tube Ferrule for Solder-Reflow-Compatible Embedded Optoelectronic Interconnections (Page 11)

James S. Sutherland (*Corning Research & Development Corporation*)
Douglas L. Butler (*Corning Research & Development Corporation*)
Jeffery S. Clark (*Corning Research & Development Corporation*)
Clifford G. Sutton (*Corning Research & Development Corporation*)
Robin M. Force (*Corning Research & Development Corporation*)
Alexander L. Cuno (*Corning Research & Development Corporation*)
Karl Heise (*Corning Research & Development Corporation*)
Lars Brusberg (*Corning Research & Development Corporation*)
Alan F. Evans (*Corning Research & Development Corporation*)
Michael de Jong (*Corning Optical Communications*)

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G. Roelkens (*Ghent University - imec*)
J. Zhang (*Ghent University - imec*)
A. De Groote (*Ghent University - imec*)
J. Juvert (*Ghent University - imec*)
N. Ye (*Ghent University - imec*)
S. Kumari (*Ghent University - imec*)
J. Goyvaerts (*Ghent University - imec*)
G. Muliuk (*Ghent University - imec*)
S. Uvin (*Ghent University - imec*)
G. Chen (*Ghent University - imec*)
B. Haq (*Ghent University - imec*)
B. Snyder (*imec*)
J. Van Campenhout (*imec*)
D. Van Thourhout (*Ghent University - imec*)
A. J. Trindade (*X-Celeprint, Limited*)
C. A. Bower (*X-Celeprint, Limited*)
J. O'Callaghan (*University College Cork*)
R. Loi (*University College Cork*)
B. Roycroft (*University College Cork*)
B. Corbett (*University College Cork*)

MC.4: Large-Scale, Automated, High-Throughput Photonic Packaging (Page N/A)

Tymon Barwicz (*IBM T.J. Watson Research Center*)
Ted W. Lichoulas (*AFL Telecommunications*)
Yves Martin (*IBM T.J. Watson Research Center*)
Yoichi Taira (*IBM T.J. Watson Research Center*)
Shotaro Takenobu (*Asahi Glass Co.*)
Alexander Janta-Polczynski (*IBM Bromont*)
Eddie L. Kimbrell (*AFL Telecommunications*)
Jae-Woong Nah (*IBM T.J. Watson Research Center*)
Elaine Cyr (*IBM Bromont*)
Richard Langlois (*IBM Bromont*)
Bo Peng (*IBM T.J. Watson Research Center*)
Robert Leidy (*GlobalFoundries*)
Hidetoshi Numata (*IBM Research - Tokyo*)
Swetha Kamlapurkar (*IBM T.J. Watson Research Center*)
Sebastian Engelmann (*IBM T.J. Watson Research Center*)
Paul Fortier (*IBM Bromont*)
Nicolas Boyer (*IBM Bromont*)

TuA - Silicon Photonics Volume Manufacturing - 8:30 am–10:00 am - Mesa Ballroom

TuA.1: Advanced Silicon Photonics for High-Speed Interconnect (Page N/A)

Peter De Dobbelaere (*Luxtera*)

TuA.2: Versatile Silicon Photonic Platform for Datacom and Computercom Applications (Page N/A)

Karim Hassan (*CEA - LETI*)
Quentin Wilmart (*CEA - LETI*)
Laeticia Adelmini (*CEA - LETI*)
Vincent Reboud (*CEA - LETI*)
Corrado Sciancalepore (*CEA - LETI*)
Daivid Fowler (*CEA - LETI*)
Stéphane Malhouitre (*CEA - LETI*)
Yvain Thonnart (*CEA - LETI*)
Olivier Castany (*CEA - LETI*)
Stéphanie Garcia (*CEA - LETI*)
Stéphane Brisson (*CEA - LETI*)
Viviane Muffato (*CEA - LETI*)
Olivier Lemonnier (*CEA - LETI*)
Karen Ribaud (*CEA - LETI*)
Philippe Grosse (*CEA - LETI*)
Benoit Charbonnier (*CEA - LETI*)
Stéphane Bernabe (*CEA - LETI*)
Ségolène Olivier (*CEA - LETI*)
Bertrand Szelag (*CEA - LETI*)
Christophe Kopp (*CEA - LETI*)

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Zhe Xuan (*University of Pennsylvania*)
Lixiong Du (*University of Pennsylvania*)
Firooz Aflatouni (*University of Pennsylvania*)

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Yuliya Akulova (*Intel*)

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Yishen Huang (*Columbia University*)

Qixiang Cheng (*Columbia University*)

Keren Bergman (*Columbia University*)

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Thomas Ferreira de Lima (*Princeton University*)

Hsuan-Tung Peng (*Princeton University*)

Mitchell A. Nahmias (*Princeton University*)

Siamak Abbaslou (*Princeton University*)

Chaoran Huang (*Princeton University*)

Alexander N. Tait (*Princeton University*)

Bhavin J. Shastri (*Princeton University*)

Paul R. Prucnal (*Princeton University*)

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Ming Gong (*University of Rochester*)

Francis Smith (*University of Rochester*)

Hui Wu (*University of Rochester*)

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Md Rezwanul H Khandokar (*University of Melbourne*)

Masuduzzaman Bakaul (*University of Melbourne and Monash University Malaysia*)

Md Asaduzzaman (*University of Melbourne*)

Stan Skafidas (*University of Melbourne*)

Thas Nirmalathas (*University of Melbourne*)

TuC - Silicon Photonics Interconnects and Fabrics - 1:30 pm–3:15 pm - Mesa Ballroom

TuC.1: PINE: An Energy Efficient Flexibly Interconnected Photonic Data Center Architecture for Extreme Scalability (Page 25)

Keren Bergman (*Columbia University*)

John Shalf (*Lawrence Berkeley National Laboratory*)

George Michelogiannakis (*Lawrence Berkeley National Laboratory*)

Sebastien Rumley (*Columbia University*)

Larry Dennison (*NVIDIA*)

Monia Ghobadi (*Microsoft Research*)

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Alexander Gazman (*Columbia University*)

Ziyi Zhu (*Columbia University*)

Meisam Bahadori (*Columbia University*)

Keren Bergman (*Columbia University*)

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Qixiang Cheng (*Columbia University*)

Liang Yuan Dai (*Columbia University*)

Meisam Bahadori (*Columbia University*)

Padraic Morrissey (*Tyndall*)

Robert Polster (*Columbia University*)

Sebastien Rumley (*Columbia University*)

Peter O'Brien (*Tyndall*)

Keren Bergman (*Columbia University*)

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Nicholas Boynton (*Sandia National Laboratories*)

Michael Gehl (*Sandia National Laboratories*)

Christina Dallo (*Sandia National Laboratories*)

Andrew Pomerene (*Sandia National Laboratories*)

Andrew Starbuck (*Sandia National Laboratories*)

Dana Hood (*Sandia National Laboratories*)

Douglas Trotter (*Sandia National Laboratories*)

Anthony Lentine (*Sandia National Laboratories*)

Christopher T. DeRose (*Sandia National Laboratories*)

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Tetsuzo Yoshimura (*Tokyo University of Technology*)

Shunya Yasuda (*Tokyo University of Technology*)

Hideaki Yamaura (*Tokyo University of Technology*)

Yusuke Yamada (*Tokyo University of Technology*)

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Zhifei Wang (*Hong Kong University of Science and Technology*)

Peng Yang (*Hong Kong University of Science and Technology*)

Yi-Shing Chang (*Intel Corp.*)

Jiang Xu (*Hong Kong University of Science and Technology*)

Xuanqi Chen (*Hong Kong University of Science and Technology*)

Zhehui Wang (*Hong Kong University of Science and Technology*)

Luan H.K. Duong (*Hong Kong University of Science and Technology*)

WA - Next Generation Hyperscale Data Centers I - 8:30 am–10:00 am - Mesa Ballroom

WA.1: The Road to 400G Optics (Page N/A)

Andreas Bechtolsheim (*Arista Networks*)

WA.2: Requirements for Next Generation Data Center (Page N/A)

Hans-Juergen Schmidtko (*Facebook*)

WA.3: Technical Feasibility of New 200 Gb/s and 400 Gb/s Links for Data Centers (Page 37)

Yi Sun (*OFS Fitel, LLC*)

Robert Lingle, Jr. (*OFS Fitel, LLC*)

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Robert Senger (*IBM TJ Watson Research Center*)

WB.2: Integrated Silicon Photonics for Future Data Center Applications (Page N/A)

Drew Alduino (*Intel Corp.*)

WB.3: Reconfigurable Integrated Photonics Based on Optical Phase Change Materials (Page N/A)

Tian Gu (*Massachusetts Institute of Technology*)

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Joseph Kahn (*Stanford University*)

Anujit Shastri (*Stanford University*)

Jose Krause (*Stanford University*)

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Nebojsa Stojanovic (*Huawei Technologies Duesseldorf GmbH*)

Fotini Karinou (*Huawei Technologies Duesseldorf GmbH*)

Cristian Prodaniuc (*Huawei Technologies Duesseldorf GmbH*)

Zhang Qiang (*Huawei Technologies Duesseldorf GmbH*)

Zhang Liang (*Huawei Technologies Duesseldorf GmbH*)

Jinlong Wei (*Huawei Technologies Duesseldorf GmbH*)

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Chenyu Liang (*Shanghai Jiao Tong University*)

Wenjia Zhang (*Shanghai Jiao Tong University*)

Zuyuan He (*Shanghai Jiao Tong University*)

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S. N. ElAhmadi (*Menara Networks*)

S. ElAhmadi (*Menara Networks*)

A. Puc (*Menara Networks*)

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Stephen Ralph (*Georgia Tech*)

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Frank Chang (*Inphi*)

WD.2: A Pair of Integrated Optoelectronic Chips for Optical Interconnects (Page 45)

Kai Liu (*Beijing University of Posts and Telecommunications*)

Yongqing Huang (*Beijing University of Posts and Telecommunications*)

Xiaofeng Duan (*Beijing University of Posts and Telecommunications*)

Qi Wang (*Beijing University of Posts and Telecommunications*)

Qi Wei (*Beijing University of Posts and Telecommunications*)

Xiaomin Ren (*Beijing University of Posts and Telecommunications*)

Shiwei Cai (*Beijing University of Posts and Telecommunications*)

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Fabio Cavaliere (*Ericsson Research*)

Luca Giorgi (*Ericsson Research*)

Luca Poti (*CNIT*)